


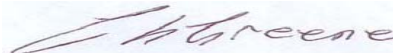




Initial  Final

<b>Contact Date:</b>	<b>Implementation Date:</b>	<b>Alert Category:</b>	<b>Alert Type:</b>	<b>PCN #:</b>
December 11, 2009	March 11, 2010	Discrete Semiconductor	Bond Wire Change	<b>PCN #: 1155 Rev00</b>
<b>TITLE</b>				
COPPER BOND WIRE IMPLEMENTATION				
<b>IMPACT</b>				
None.				
<b>DESCRIPTION OF CHANGE</b>				
To improve selected electrical and mechanical properties by changing from gold to copper bond wire. Copper wire devices will be phased in gradually from the date of implementation.				
<b>PRODUCTS AFFECTED</b>				
FMMT38CTA, FMMT38CTC FMMT593TA, FMMT593TC FZT849TA, FZT849TC FZT788BTA, FZT788BTC				
<b>WEB LINKS</b>				
<b>Manufacturer's Notice:</b>	<a href="http://www.diodes.com/quality/pcns/">http://www.diodes.com/quality/pcns/</a>			
<b>For More Information Contact:</b>	<a href="http://www.diodes.com/contacts/">http://www.diodes.com/contacts/</a>			
<b>Data Sheet:</b>	<a href="http://www.diodes.com">http://www.diodes.com</a>			
<b>DISCLAIMER</b>				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				
<b>PCN APPROVAL</b>				
<b>Signatories</b>	<b>Name</b>	<b>Signature</b>	<b>Date</b>	
Signature of Sr. Vice President, Sales & Mktg.	Mark King		December 4,2009	
Signature of VP Corporate Administration	Ed Tang		December 1,2009	
Signature of VP Product Development	Francis Tang		December 4,2009	
Signature of European President & VP Sales and Mktg.	Colin Greene		December 1,2009	
Signature of Director of QA, HR & IT	Dave Benstead		December 1,2009	
Signature of European Sales Manager	Oliver Woyke		December 1,2009	